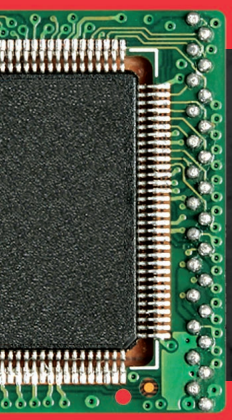


DRAM MEMORY & FLASH STORAGE

DRAM, FLASH/SSD, Persistent Memory & Customized Packaging

viking TECHNOLOGY

ENGINEERING. DESIGN. MANUFACTURING.

With over 25 years of Memory and Storage experience in supporting some of the world's biggest OEMs, Viking Technology has the capability to support any memory requirements for any market. Whether it's standard off-the-shelf solutions or customized form factors, Viking Technology can support it.

VIKING TECHNOLOGY

Viking Technology is a global technology leader in the field of DRAM memory & Flash storage solutions ranging from high-performance computing SSDs to small form factor flash DRAM modules optimized for industrial, telecommunications, military/defense, and enterprise markets. Viking Technology broadens its technology leadership with several advanced technologies such as memory packaging, multi-chip packaging, system-in-package, and storage class memory.

Viking Technology's comprehensive memory product offerings include Enterprise Class & Industrial Grade SSDs available across a wide portfolio of standard and OEM customized form-factors (2.5", 1.8" SlimSATA, mSATA, M.2, PCIe/NVMe SSDs, SATADIMM™, Discrete Flash Cards and eUSB). Viking Technology also supports the broadest range of DDR4, DDR3, DDR2, DDR1 and custom modules; from High-Density to Small-Form Factor with Error Checking and Correction (ECC Memory).

Viking Technology also specializes in DRAM and Flash Multi-chip packaging, allowing for higher density packages optimized for the military and aerospace environments. Viking Technology's Parallel family of Packaged products are multi-chip package (MCP) solutions that are bare die and wafer level stacked, capable of reducing the overall footprint of memory modules into a single chip. These MCP solutions are military tested, defense avionics ready with future generations optimized for radiation tolerant and space compliant.

VIKING TECHNOLOGY PRODUCT PORTFOLIO

Viking Technology's comprehensive DRAM Memory and Flash Storage product offerings include Enterprise Class, Industrial Grade, and Military optimized solutions across a wide portfolio of standard and OEM customized form-factors.

PARALLEL FAMILY OF DIE STACKED SOLUTIONS

- **ParallelCell**
  Multi-chip packaged (MCP) memory solution optimized for Military, Industrial and Embedded applications with temperature ranges of -55°C to +125°C. A full size DRAM Module in a DRAM Chip form factor.
- **Parallel SSD**
  Ultra-high density Flash NAND solutions in a NAND Chip form factor. Optimized for embedded applications, ParallelSSD supports up to 512GB of managed NAND in a 16mm x 20mm footprint.
- **Parallel SiP**
  A MRAM based System-in-Packaged (SiP) solution coupling non-volatile memory with DRAM protocols and FPGA controller for a complete persistent memory system in package.

FLASH/SSD STORAGE

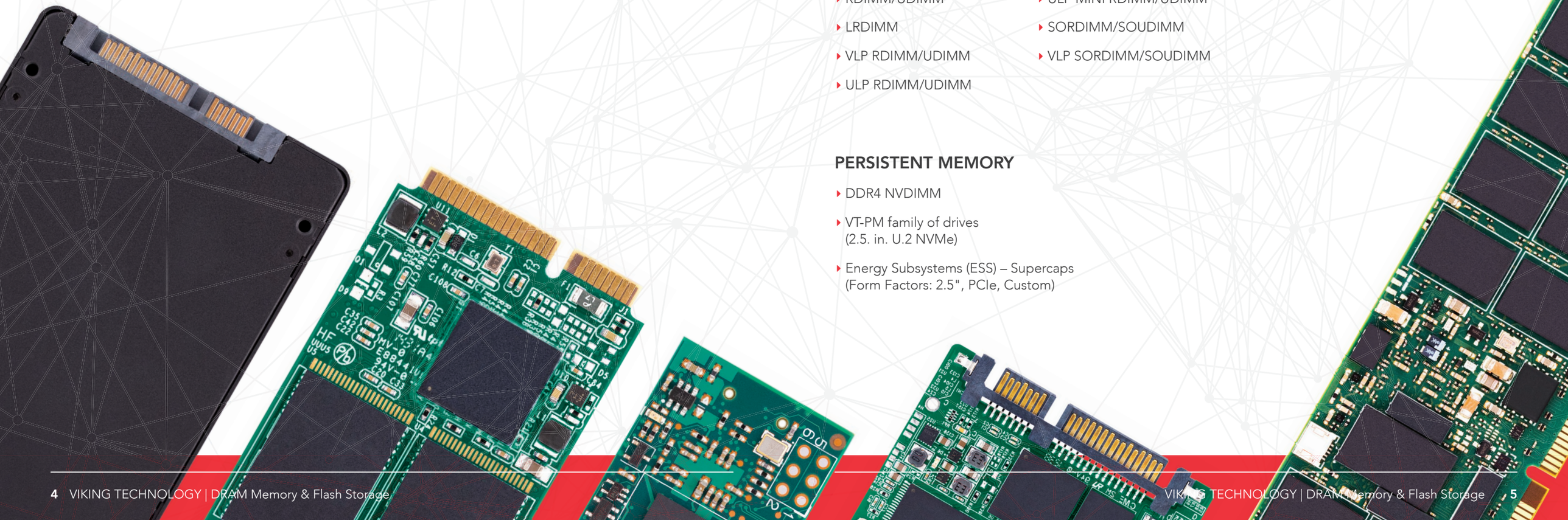
- 2.5 in. SSD
- 1.8 in. SSD
- M.2 SSD
- slimSATA
- mSATA
- eUSB
- USB Thumbdrives
- SD, microSD cards
- Custom Designs

DRAM (DDR4, DDR3, DDR2, DDR1)

- Multi-Chip Package (MCP)
- RDIMM/UDIMM
- LRDIMM
- VLP RDIMM/UDIMM
- ULP RDIMM/UDIMM
- MINI RDIMM/UDIMM
- ULP MINI RDIMM/UDIMM
- SORDIMM/SOUDIMM
- VLP SORDIMM/SOUDIMM

PERSISTENT MEMORY

- DDR4 NVDIMM
- VT-PM family of drives
  (2.5. in. U.2 NVMe)
- Energy Subsystems (ESS) – Supercaps
  (Form Factors: 2.5", PCIe, Custom)



PARALLEL FAMILY

Viking Technology Parallel Family of Die Stacked solutions are part of the extreme density line of products dedicated and optimized for the embedded, military/defense, and industrial market. Designed to provide a significantly higher memory density per cubic inch, these solutions can reduce design footprints up to 85% compared to traditional DRAM and Flash modules.

These performance and density milestones will critically change the way future systems hardware are designed and deployed.

PARALLEL FAMILY OF PACKAGE SOLUTIONS

Very small footprint: Saves up to 85% board space vs. Standard DRAM & Flash Modules	Rugged: Soldered-down – No interface connectors	Ultra-high memory density per cubic in.
DRAM, NAND & System Packaged Modules	Superior signal integrity	Very high memory bandwidth per cu. in.

Ultra-Dense Line of Die-Stacked Solutions

Viking Technology's Parallel family of Packaged products are multi-chip package (MCP) and system-in-packaged (SiP) solutions that are bare die and wafer level stacked, capable of reducing the overall footprint of memory modules into a single chip. These MCP/SiP solutions are military tested, defense, and avionics ready with future generations optimized for radiation tolerant and space compliant.

PARALLELCELL

Full single rank DDR4 memory channel solution in a BGA package with data width at x72 (64 data bits plus ECC)

- Ultra-dense: 15mm x 20mm
- Up to 16GB
- Temperature range: -55°C to +125°C
- Up to 2667 MT/sec
- Reliability: 100% burn-in

PARALLELSSD

Ultra-high capacity Solid State Drive solution in a BGA package, optimized as managed NAND for embedded applications

- Ultra-dense: 16mm x 20mm
- Up to 512GB
- Temperature range: -55°C to +105°C
- Interface: SATA/NVMe
- Performance: up to 1400MB/s (read) / 650MB/s (write)

PARALLELSiP

MRAM based System-in-Packaged (SiP) providing persistent memory chips for Military/Defense, medical, and gaming markets

- Ultra-dense: 14mm x 14mm
- Up to 512MB
- Interface: PCIe, QSPI
- Ultra-high endurance: 1B+ power cycles
- True persistent memory class

FLASH/ SSD

Viking Technology offers a wide portfolio of Flash & SSD storage solutions that comes in a variety of form factors such as 2.5in, 1.8in, M.2, slimSATA, mSATA, eUSB, USB FlashDrives, SD, microSD and custom build.

As well, Viking Technology utilizes various NAND and Controller vendors to help insulate our customers against single NAND supply issues as well as price competitiveness. This also allows Viking Technology to provide the best form fit and function to each and every application.

Viking Technology's line of memory/storage solutions with extended temperature support are built with the most stringent of requirements in mind, with extreme temperature ranges, high humidity support, shock resistance, and ruggedization. Viking's extended temperature solutions ranges from standard commercial (0°C to +70°C) & industrial temperatures (-40°C to +85°C) as well as customized temperature ranges of up to +170°C.

MEASURES OF QUALITY

- MTBF calculation using the Belco remodeling method
- Real-time monitoring of field DPPM
- Weekly reviews of MRB with closed loop feedback action
- Weekly monitoring of First pass yield, RTY, scrap, in process defects
- Bi-annual CSI monitoring of all suppliers
- Quarterly SSI monitoring of all suppliers
- Environmental awareness with ISO 14000
- Corporate CSR
- Certified to ISO 9000, TL 9000 and AS 9100
- In-house reliability tools and thermal-cycle, shock chambers
- Local MIL 810 testing and certification available
- In-house Failure Analysis
- All inspectors IPC CERTIFIED
- All QE's have ASQ certifications
- In-house designed test programs

ENVIRONMENTAL/RELIABILITY

- Mil-Std-810F Test Suite
- Altitude
- High temp operating
- Low temp operating
- Humidity
- Thermal shock
- EMC
- Thermal Cycling
- Blowing dust
- Vibration
- Mechanical shock
- Acceleration
- Explosive atmosphere

FLASH/SSD EXTENDED TEMPERATURE SUPPORT

FORM FACTOR	INTERFACE	CAPACITY	TEMPERATURE SUPPORTED			
3.5 IN. SSD	SAS	25TB/50TB	Commercial			
2.5 IN. SSD	SAS/NVMe/PCIe	up to 30TB	Commercial			
2.5 IN. SSD	SATA	up to 8TB	Commercial	Industrial	Automotive	Military
M.2 SSD	SAS/NVMe/PCIe	up to 4TB	Commercial			
M.2 SSD	SATA	up to 4TB	Commercial	Industrial		
SlimSATA/mSATA	SATA	up to 1TB	Commercial	Industrial		
eUSB	USB	up to 32GB	Commercial	Industrial	Automotive	Military
SD/microSD	SD	up to 256GB	Commercial	Industrial		
Discrete Flash Card	PATA	up to 32GB	Commercial	Industrial	Automotive	Military
USB ThumbDrive	USB	up to 512GB	Commercial	Industrial	Automotive	Military
Stacked Solutions	Custom	up to 32GB	Commercial	Industrial	Automotive	Military

2.5 inch SSD

Viking Technology's 2.5 Inch SSDs are built with the understanding of OEM expectations through comprehensive and exhaustive design verification and production test methods. Viking's 2.5 Inch SSDs for the embedded and Industrial market delivers the highest levels of quality, environmental ruggedness and endurance. As well, the 2.5 Inch SSDs can be leverage for the Enterprise market with engineered options for the highest levels of performance and reliability, Viking featuring multiple interfaces including SATA, SAS and PCIe/NVMe that delivers high performance with reliability.

AVAILABLE IN SATA, SAS, PCIE/NVME AND U.2

- Supports MLC/SLC/3D NAND Configurations
- Advanced SSD-specific SMART command support
- Package and firmware customization
- Locked BOM
- Data path protection, Encryption, Max Write performance

MARKETS SERVED

Data Center | HDD | Video | Telecom | Aerospace | Servers | Storage

M.2 SSD

Viking Technology's M.2 Solid State Drive (SSD) is a high-performance, high-capacity flash solution optimized for the embedded and server market. The M.2 SSD is a caseless drive with either a SATA or PCIe/NVMe connector; delivering high-bandwidth READs and WRITEs at a fraction of the size of a standard 2.5 inch SSD. The thin form factor comes in a variety of sizes best fit for the customer's system requirements.

M.2 is a new storage form factor optimized specifically for embedded solutions to increase overall performance and capacity.

VIKING CUSTOMIZATION OPTIONS:

Client and Enterprise options

3D NAND Options and SLC

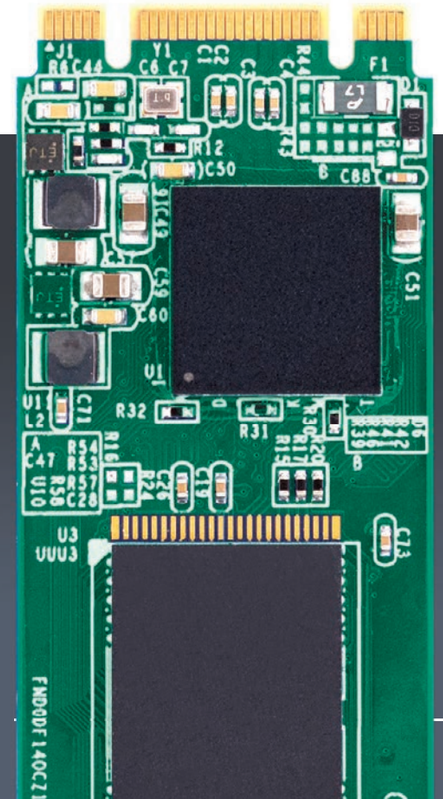
Low capacity form factor 22mm x 42mm

High capacity form factor 22mm x 110mm

Form Factor options 22mm x (42, 60, 80, 110) mm

MARKETS SERVED

Servers | POS | Cache | Industrial | Mobile | Digital Signage | Boot Device

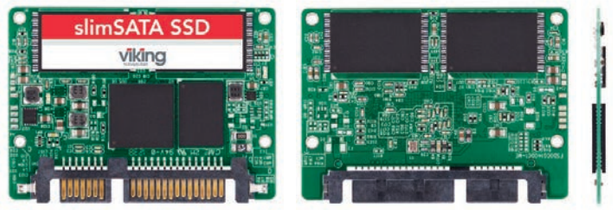


- Data path protection, Encryption, Max Write performance
- Ultra high-performance
- Advanced SSD-Specific SMART command support
- Low & High capacity form factor options

slimSATA & mSATA SSDs

slimSATA & mSATA SSD are solid state drive solutions ideal for space-constrained embedded server & storage systems, telecommunications, automotive, gaming and many industrial applications. Both solutions deliver outstanding performance in a small, industry standard form factor and features intelligent flash management techniques to optimize endurance and wear-leveling. Both drives come in a variety of performance and capacity as well as ruggedization and increased endurance.

- Available in SATA-III 6Gbs
- Read intensive & Low cost solution options
- Max write performance
- Supports MLC/SLC/3D NAND Configurations
- Advanced SSD-specific SMART command support
- Package and firmware customization
- Insulation against single NAND supply issues
- Locked BOM



MARKETS SERVED

Servers | Cache | Data Acceleration | Factory Automation | Boot Device | Medical Equipment

eUSB

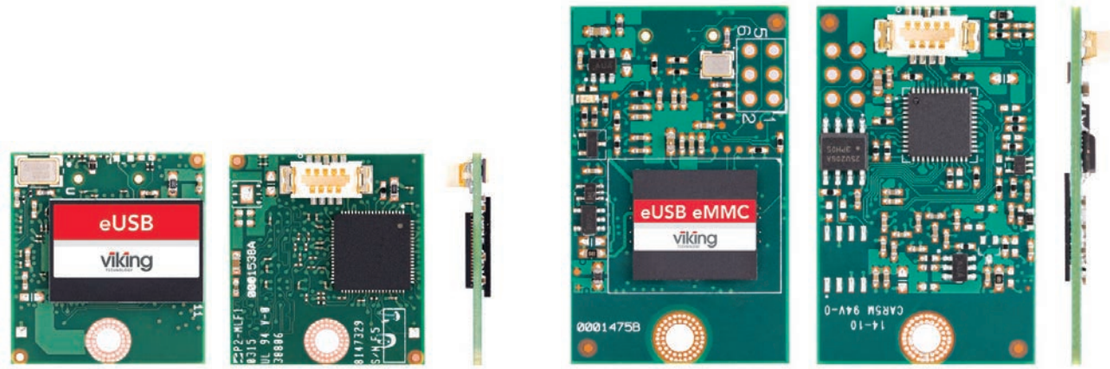
The embedded USB (eUSB) module from Viking Technology provides a rugged, reliable and cost effective non-volatile memory solution to OEM customers in the Networking, Embedded and Industrial markets. eUSB modules are secure pluggable USB 2.0/3.0 devices with built-in ECC and global wear-leveling for exceptional reliability and product lifetime. Viking eUSB modules are available in capacities up to 128GB and deliver performance up to 35 MB/s. Available in both industry standard, low profile, and custom versions, as well as 3.3V and 5V operation.

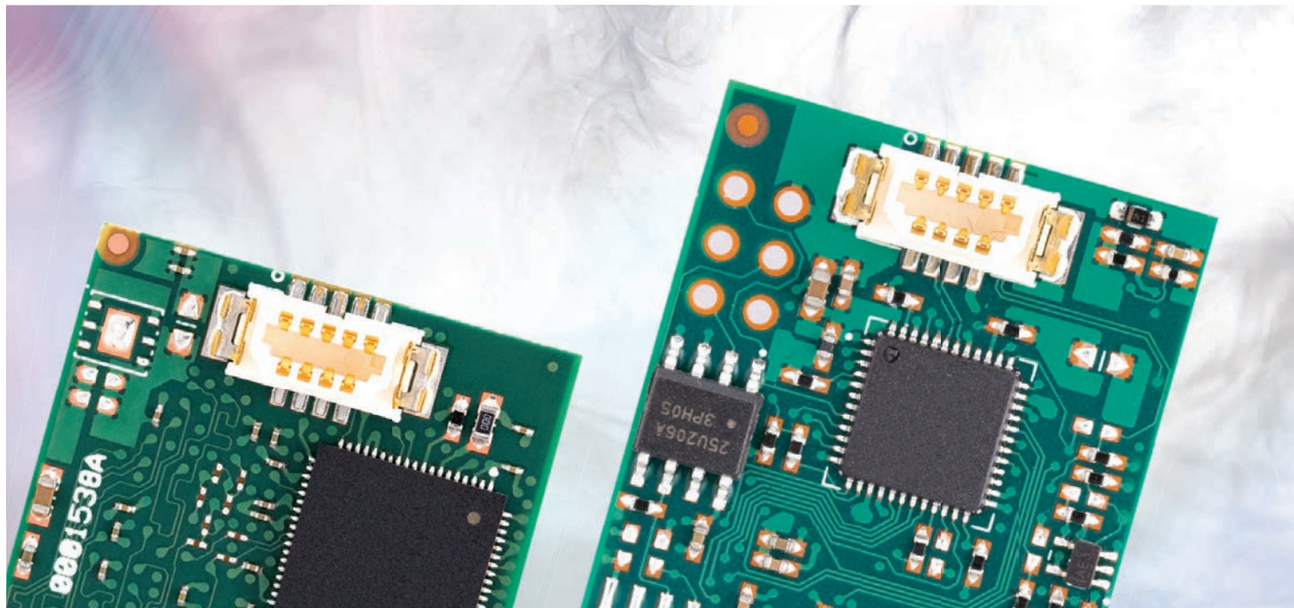
eUSB

- Reduced size eUSB
- Optimized for space constraint routers/switches
- Available in iTemp & cTemp configurations
- Screw mountable for ruggedization

eUSB eMMC

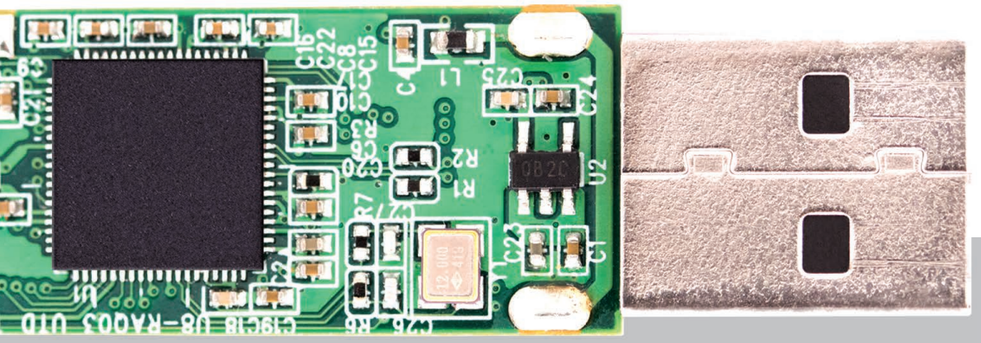
- Cost effectiveness utilizing eMMC Flash
- Low-cost endurance alternative to SLC NAND
- ECC and Data Management
- Highest endurance
- Extremely low cost alternative





USB Thumbdrive

Viking Technology USB Thumbdrive, also known as a USB Flash Drive, is a embedded/industrial Flash storage device that includes flash memory with an integrated USB 2.0/3.0 interface. The USB Thumbdrive comes in a variety for sizes best fit for any application and space constraint systems.



- Optimized for space constraint routers/switches
- Available in iTemp & cTemp configurations
- Available in capacities up to 512GB
- Utilizes SLC/MLC/3D NAND
- Locked BOM
- Package & Firmware customization
- Conformal coated configuration

- USB 3.0 high speed compatible (supports Bulk-Only transport protocol)*
- Write Protect
- Drive Activity indicator signal (Blue LED is on when USB is active)
- Solid state, Non-volatile NAND Memory
- RoHS Compliant

**With exception of 3.3V only operation, USB specification is 5V*

MARKETS SERVED

IP Routing | Switches | Servers | Cache | Data Acceleration | Factory Automation | Medical Equipment | Boot Device | Data Logging

SD & microSD

Viking Technology Secure Digital Cards (SD) and microSD cards are powerful, highest capacity memory card that delivers maximum speed for performance, reliability, and security to the most demanding of embedded solutions. These removeable cards are optimized for the embedded market with high-shock tolerance, high-temperature configurations, and ruggedization for extreme environments.

- Capacities up to 256GB
- Superior wear leveling
- High Performance
- SD Security specs v. 2.0
- Mechanical write protection switch
- Supports commercial and industrial temperature

MARKETS SERVED

Servers | Cache | Data Acceleration | Factory Automation | Medical Equipment | Boot Device | Switches | Data Logging

DRAM

Viking Technology has over two decades of experience supporting Original Equipment Manufacturers (OEMs) with the industry's most comprehensive range of DRAM modules. Leveraging advanced packaging expertise, locked BOM control, and AS9100, TL 9000, and ISO 14001 certified facilities, Viking Technology is able to deliver the highest quality DRAM modules that meet the requirements of the Enterprise, Telecommunications and Embedded markets.

Viking Technology also specializes in Stacking Technologies that allow for ultra-high density memory modules. Viking Technology's 3rd Generation of Patented stacking, the VT-Stack™ enables OEM customers that are designing solutions with DRAM, NAND Flash or even next generation memory technologies such as ReRAM, MRAM, or PhaseChange, to optimize the performance and design cycle of their products.

DDR4, DDR3, DDR2, DDR1

From enterprise to Embedded to network infrastructure, OEMs from around the world trust in Viking Technology's DRAM modules and technology. Viking has more than just a long history of supporting OEMs with edging lead DRAM technology but also provides its customers with legacy support. With the industry's broadest offering of standard DRAM modules, specialty modules, and small form factor modules, Viking is not only a provider of high-quality memory but a partner in DRAM technology.

RDIMM/UDIMM

DDR4: 133.35mm
DDR3: 30.00mm
DDR2: 30.00mm

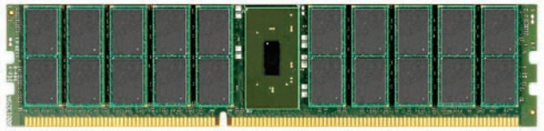
DDR2, DDR3, DDR4: 133.35mm

MINI RDIMM/UDIMM

DDR4: 31.25mm
DDR3: 30.00mm
DDR2: N/A

DDR2, DDR3: 82mm
DDR4: 80mm

LRDIMM



DDR4: 31.25mm
DDR3: 30.00mm
DDR2: 30.00mm

DDR2, DDR3, DDR4: 133.35mm

VLP MINI RDIMM/UDIMM

DDR4: 18.75mm
DDR3: 18.75mm
DDR2: N/A

DDR2, DDR3: 82mm
DDR4: 80mm

VLP RDIMM/UDIMM

DDR4: 18.75mm
DDR3: 18.75mm
DDR2: 18.25mm

DDR2, DDR3, DDR4: 133.35mm

ULP MINI RDIMM/UDIMM

DDR4: 17.78mm
DDR3: 17.78mm
DDR2: 17.78mm

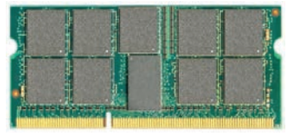
DDR2, DDR3: 82mm
DDR4: 80mm

ULP RDIMM/UDIMM

DDR4: 17.78mm
DDR3: 17.78mm
DDR2: 17.78mm

DDR2, DDR3, DDR4: 133.35mm

SORDIMM/SOUDIMM



DDR4: 30.00mm
DDR3: 30.00mm
DDR2: 30.00mm

DDR2, DDR3: 67.6mm
DDR4: 69.6mm

VLP SORDIMM/SOUDIMM

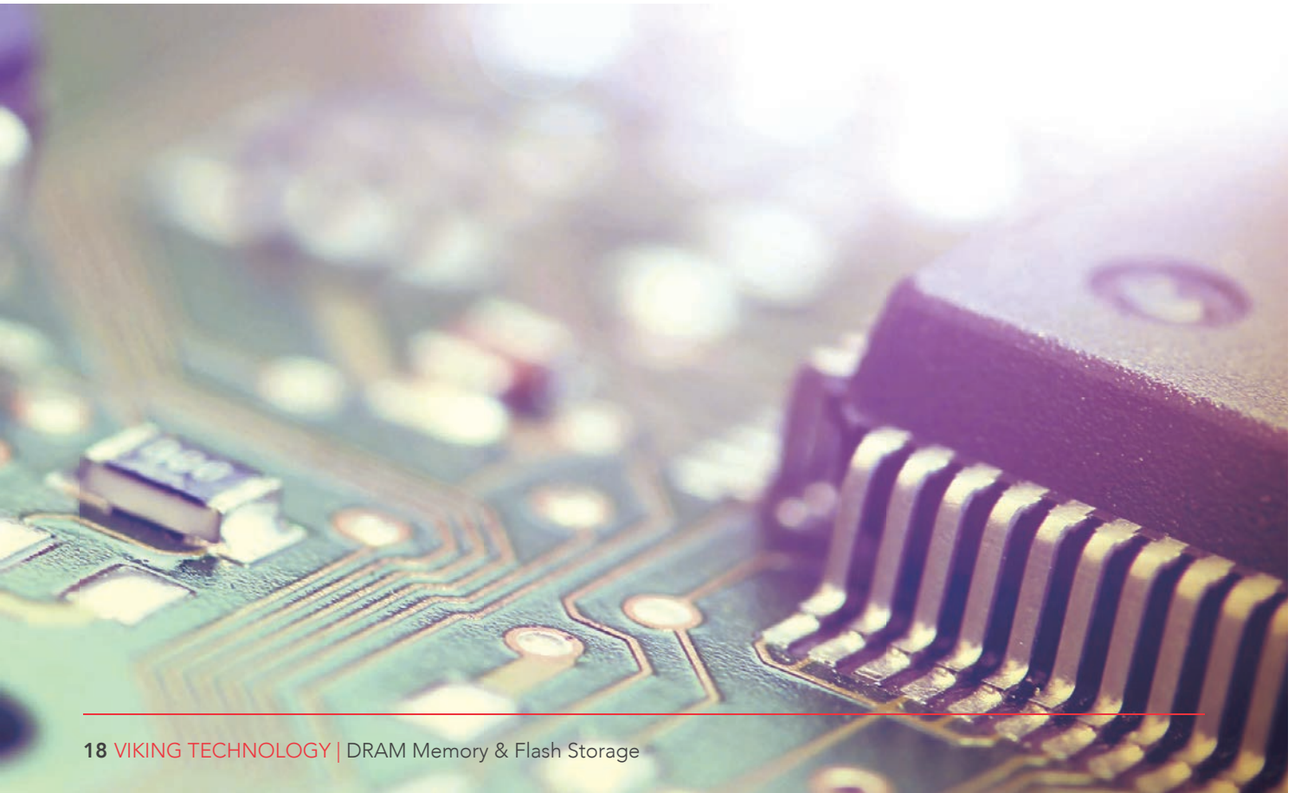
DDR4: 18.75mm
DDR3: 18.75mm
DDR2: N/A

DDR2, DDR3: 67.6mm
DDR4: 69.6mm

DENSITIES AND CONFIGURATIONS

- Broadest DRAM Offering
- JEDEC Standard
- Low-cost options
- Customized Testing
- Bill of Materials (BOM)
- Extending Burn-in Testing
- Thermal Modeling
- Small Form Factors

SPECIFICATION		DDR1	DDR2	DDR3	DDR4
CHIP DENSITY	Min	256MB	512MB	1GB	4GB
	Max	512MB	2GB*	8GB*	32GB
MODULE DENSITY	Max	4GB	16GB	64GB	128GB
SPEED	Slowest	200MT/s	400MT/s	800MT/s	1600MT/s
	Fastest	400MT/s	800MT/s	1866MT/s	2666MT/s
PACKAGE	Package	TSOP/FBGA	FBGA	FBGA	FBGA



EXTENDED TEMPERATURE MEMORY & STORAGE SOLUTIONS

Viking Technology's line of memory/storage solutions with extended temperature support are built with the most stringent of requirements in mind, with extreme temperature ranges, high humidity support, shock resistance, and ruggedization. Viking's extended temperature solutions ranges from standard commercial (0°C to +70°C) & industrial temperatures (-40°C to +85°C) as well as customized temperature ranges of up to +170°C. These extended temperature solutions can be found in applications used in mountainous regions to deserts and even in arctic conditions for Oil and Gas down-hole drilling. Beyond the temperature ranges, each solution can be customized as a ruggedized memory/storage device built to resist larger amounts of shock and vibrations. These solutions offer the utmost in performance and reliability in challenging, real-world conditions.

DRAM EXTENDED TEMPERATURE SUPPORT

FORM FACTOR	DDR4	DDR3	DDR2	DDR1
LRDIMM	Up to 128GB	Up to 32GB		
RDIMM	Up to 64GB	Up to 32GB	Up to 16GB	Up to 4GB
UDIMM	Up to 64GB	Up to 16GB	Up to 8GB	Up to 2GB
VLP RDIMM	Up to 32GB	Up to 16GB	Up to 8GB	Up to 4GB
VLP UDIMM	Up to 32GB	Up to 8GB	Up to 4GB	Up to 1GB
ULP RDIMM	Up to 32GB	Up to 16GB	Up to 8GB	
MiniRDIMM	Up to 16GB	Up to 16GB	Up to 8GB	Up to 1GB
MiniUDIMM	Up to 16GB	Up to 16GB	Up to 4GB	Up to 1GB
VLP MiniRDIMM	Up to 16GB	Up to 8GB	Up to 4GB	NA
VLP MiniUDIMM		Up to 8GB	Up to 4GB	NA
ULP MiniRDIMM	Up to 16GB	Up to 8GB		NA
ULP MiniUDIMM	Up to 16GB	Up to 8GB		NA
SORDIMM	Up to 16GB	Up to 16GB	Up to 4GB	Up to 1GB
SOUDIMM	Up to 16GB	Up to 8GB	Up to 4GB	Up to 1GB
SOCDIMM	NA	NA	Up to 4GB	Up to 1GB
VLP SORDIMM	Up to 8GB	Up to 8GB		
TEMPERATURE RANGE				
	Commercial	Commercial	Commercial	Commercial
	Industrial	Industrial	Industrial	Industrial
	Automotive	Automotive		
	Military	Military		

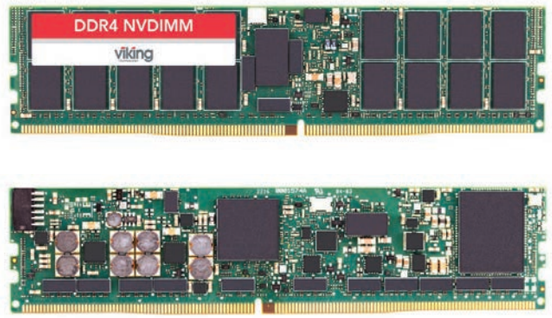
PERSISTENT MEMORY

Viking Technology has a strong legacy in developing Persistent Memory solutions over several generations of products; ranging from Non-Volatile DIMMs (NVDIMMs) to persistent drive form factor solutions with DRAM enablement.

These persistent solutions are delivering the key components to enterprise customers looking to enable the next generation of computing and storage architectures.

DDR4 NVDIMM

Viking's (NVDIMM) DDR4 Non-Volatile DIMM, delivers both performance and reliability to enterprise applications. This non-volatile memory module has been designed to be integrated into Intel's new NVDIMM enabled servers via DDR4 DIMM sockets and designed to preserve critical data in the event of a power or system failure. Viking's NVDIMM enables the host system to recover from a failure event with simplicity and ease.



NVDIMM – N

Memory mapped DRAM with no system access to flash.

- Low-Capacity (2GB - 32GB)
- Very-low Latency (10s of nanoseconds)

NVDIMM Energy Sub-System (ESS)

The NVDIMM is a DDR4 Non-Volatile DIMM enabled by an energy subsystem (ESS) which provides enough power to the module in an event of power-loss to safely store all mission critical data. Viking's ESS modules come in a variety of standard & custom form factors from 2.5in, PCIe, FanBay and special builds, with or without casing. As well, Viking Technology has the ability to customize any ESS to fit within any customer server/storage appliance.

VT-PM Drive

VT-PM drives, part of Viking's persistent memory technology family of products, are 2.5" U.2 NVMe PCIe Gen3 drives optimized to Enterprise-grade with Radian Memory System's architecture technology. The VT-PM8 and VT-PM16 are persistent memory drives that deliver performance and unlimited write endurance similar to that of DRAM, while simultaneously providing the data persistence desired for enterprise applications.

ADVANTAGES

Simple, Reliable, Persistent	Supports the NVMe Command Set	Hot Swap, Live Insertion, Surprise Remove
No Remote Capacitor Packs or Cabling	Interface Simplicity	OEM Lifecycle Monitoring Diagnostics

- 2.5" U.2 NVMe Drive form factor
- Lowest latency NVMe device regardless of queue depth
- Internal super-capacitor system fully contained in single drive
- NVMe (block) and byte addressable mmap access
- Dual Port 2x2 or Single Port x4 mode

SPECIFICATIONS

Capacity	16GB (8GB: VT-PM8)
U.2 2.5" NVMe form factor	Length: 100mm, Height: 15.0mm, Width: 69.75mm
Dual Port and Single Port Modes	Dual Port 2x2 lane configuration or Single Port x4 lane configuration
PCIe x4 Gen3	Compliant with PCI-Sig PCIe 3.0 Base specification
NVMe Command Set	NVM Express specification 1.0
NV-RAM Capacity	8GB, 16GB based upon DDR4 at 2,400 MHz with internal power backup system
DRAM ECC	64-bit data/8-bit ECC code detects double bit errors and corrects single bit errors
NAND ECC	Hardware LDPC engine
NVMe Engines	Supports NVMe command set, submission/completion queues and MSI-X vector interrupts
Programmed I/O (PIO)	Fixed BAR provides support for direct 4 byte addressable (dword) host access by mapping memory (mmap) into host PCI address space with configurable window size
Maximum Payload Size	Configurable to 128B or 256B single packet size
BIST and Health Monitoring	Provides OEMs the ability to monitor environmental status, component health, and log statistics for continuous product life cycle management
Field Upgradeable Firmware Updates	Mechanism for upgrading firmware in the field via host control (no drive removal necessary)
Internal Supercapacitor Module	Field replaceable assembly
Power Requirements (+12V rail)	Typical Maximum: 13.5W at 40°C Recharge Cycle: Up to 17W at 40°C with concurrent r/w operations
Supercapacitor Recharge Time	38 seconds
Temperature	Operating: 0° to 40°C at 100 LFM Storage: 40°C to 85°C
Weight	.295 lbs.
Shock/Vibration	Operating: 5 G Non-Operating: 10 G
ESD	1,500 volts, human body model
MTBF	1M hours
Device Drivers	NVMe Linux 4.10 and above

Radian MEMORY SYSTEMS

Utilizes Radian Memory Systems technology

VIKING TECHNOLOGY
A DIVISION OF SANMINA CORPORATION

GLOBAL
Customer Connected

MATURE
Developed Over 25 Years

COMPLETE SYSTEM
Consistently Deployed

1200+ CUSTOMERS
Diverse Customer Base

30,000+ SUPPLIERS
Integrated

- Founded in 1980 in San Jose, California
- Global footprint: 75 facilities in 25 countries
- $8.23B revenue
- 45,000 employees

WELCOME TO THE SANMINA FAMILY

Sanmina makes some of the most complex and innovative optical, electronic and mechanical products in the world. Recognized as a technology leader, Sanmina provides end-to-end design, manufacturing and logistics solutions, delivering superior quality and support to Original Equipment Manufacturers (OEMs) primarily in the communications networks, computing and storage, medical, defense and aerospace, industrial and semiconductor, multimedia, automotive and clean technology sectors.

Sanmina maintains a network of regional design, quick turn, New Product Introduction (NPI) facilities and repair centers, in addition to a complete global footprint of manufacturing operations in 23 countries on six continents. Each day, in every region of the world, Sanmina designs, manufactures ships and repairs complex, mission-critical products. For over 30 years, customers have come to expect quality, delivery, reliability and service from Sanmina. Together we build productive relationships based on exceptional customer satisfaction.

Viking Technology is proud to be part of the Sanmina family, with a globally recognized name in technology and trusted partner in all of manufacturing.

END-TO-END SERVICES

ADVANCED TECHNOLOGY FOR COMPLEX PRODUCTS

ENGINEERING AND NPI CAPABILITIES

STRONG LIQUIDITY & FINANCIALS

FLASH/SSD PART NUMBERS

FORM FACTOR	INTERFACE	TEMP	CAPACITY	VIKING PN#	CONTROLLER	NAND
1.8" SATA	5mm	-40°C to+85°C	960	VRFS11960GEIHWT3	SM2259	TSB BiCS 3D
1.8" SATA	5mm	-40°C to+85°C	480	VRFS11480GEI5WT3	SM2259	TSB BiCS 3D
1.8" SATA	5mm	-40°C to+85°C	240	VRFS11240GEI5WT3	SM2259	TSB BiCS 3D
1.8" SATA	5mm	-40°C to+85°C	120	VRFS11120GEI5WT3	SM2259	TSB BiCS 3D
1.8" SATA	5mm	-40°C to+85°C	60	VRFS11060GEI5WT3	SM2259	TSB BiCS 3D
2.5" PCIe	7mm	0°C to+70°C	960	VWFN22960G2CTWW	WD	TSB BiCS 3D
2.5" PCIe	7mm	0°C to+70°C	7682	VWFN227T682CVWW	WD	TSB BiCS 3D
2.5" PCIe	7mm	0°C to+70°C	3842	VWFN223T842CAWW	WD	TSB BiCS 3D
2.5" PCIe	7mm	0°C to+70°C	1920	VWFN221T922CTWW	WD	TSB BiCS 3D
2.5" PCIe	7mm	0°C to+70°C	6400	VSFN256T40YC8WSA	Samsung	Samsung
2.5" PCIe	7mm	0°C to+70°C	3200	VSFN253T20YC4WSA	Samsung	Samsung
2.5" PCIe	7mm	0°C to+70°C	1600	VSFN251T60YC4WSA	Samsung	Samsung
2.5" PCIe	7mm	0°C to+70°C	960	VSFN22960GHCLWSA	Samsung	Samsung
2.5" PCIe	7mm	0°C to+70°C	7680	VSFN227T68HC8WSA	Samsung	Samsung
2.5" PCIe	7mm	0°C to+70°C	3840	VSFN223T84HC8WSA	Samsung	Samsung
2.5" PCIe	7mm	0°C to+70°C	1920	VSFN221T92HCLWSA	Samsung	Samsung
2.5" PCIe	7mm	-40°C to+85°C	960	VRFN22960GJIHWT3	SM2262	TSB BiCS 3D
2.5" PCIe	7mm	-40°C to+85°C	480	VRFN22480GJI5WT3	SM2262	TSB BiCS 3D
2.5" PCIe	7mm	-40°C to+85°C	240	VRFN22240GJI5WT3	SM2262	TSB BiCS 3D
2.5" PCIe	7mm	-40°C to+85°C	1920	VRFN221T92JIFWT3	SM2262	TSB BiCS 3D
2.5" PCIe	7mm	-40°C to+85°C	120	VRFN22120GJI5WT3	SM2262	TSB BiCS 3D
2.5" PCIe	7mm	-40°C to+85°C	60	VRFN22060GJI5WT3	SM2262	TSB BiCS 3D
2.5" PCIe	PCIe	0°C to+70°C	60	VRFN22060GJC5WT3	SM2262	TSB BiCS 3D
2.5" SAS	15mm	0°C to+70°C	960	VSF225960G4CFWSA	Samsung	Samsung
2.5" SAS	15mm	0°C to+70°C	7680	VSF2257T684C8WSA	Samsung	Samsung
2.5" SAS	15mm	0°C to+70°C	3840	VSF2253T844C8WSA	Samsung	Samsung
2.5" SAS	15mm	0°C to+70°C	30720	VSF22530T74C8WSA	Samsung	Samsung
2.5" SAS	15mm	0°C to+70°C	1920	VSF2251T924C4WSA	Samsung	Samsung
2.5" SAS	15mm	0°C to+70°C	15360	VSF22515T34C8WSA	Samsung	Samsung
2.5" SATA	7mm	0°C to+70°C	512	VWFS22512G2CHWW3	WD	TSB BiCS 3D
2.5" SATA	7mm	0°C to+70°C	1000	VWFS22001T2CHWW3	WD	TSB BiCS 3D
2.5" SATA	7mm	0°C to+70°C	960	VSFS22960GFCLWSAE	Samsung	Samsung
2.5" SATA	7mm	0°C to+70°C	7680	VSFS227T68FC8WSAE	Samsung	Samsung
2.5" SATA	7mm	0°C to+70°C	480	VSFS22480GFCFWSAE	Samsung	Samsung
2.5" SATA	7mm	0°C to+70°C	3840	VSFS223T84FCLWSAE	Samsung	Samsung
2.5" SATA	7mm	0°C to+70°C	240	VSFS22240GFCFWSAE	Samsung	Samsung
2.5" SATA	7mm	0°C to+70°C	1920	VSFS221T92FCLWSAE	Samsung	Samsung
2.5" SATA	7mm	-40°C to+85°C	960	VRFS22960GEIHWT3	SM2259	TSB BiCS 3D
2.5" SATA	7mm	-40°C to+85°C	480	VRFS22480GEI5WT3	SM2259	TSB BiCS 3D
2.5" SATA	7mm	-40°C to+85°C	240	VRFS22240GEI5WT3	SM2259	TSB BiCS 3D
2.5" SATA	7mm	-40°C to+85°C	120	VRFS22120GEI5WT3	SM2259	TSB BiCS 3D
2.5" SATA	7mm	-40°C to+85°C	60	VRFS22060GEI5WT3	SM2259	TSB BiCS 3D
3.5"	SAS 6Gbs	0°C to+50°C	45800	VNF33145T834CCMHB	Custom 6Gb/s SAS	Custom
3.5"	SAS 6Gbs	0°C to+50°C	22900	VNF33122T934CCMHB	Custom 6Gb/s SAS	Custom
eMMC	eMMC	0°C to+70°C	8	VSFEMMC8192CWSF	Samsung	Samsung
eMMC	eMMC	0°C to+70°C	256	VSFEMMC256GCC1	Samsung	Samsung
eMMC	eMMC	0°C to+70°C	128	VSFEMMC128GCC1	Samsung	Samsung
eMMC	eMMC	0°C to+70°C	64	VSFEMMC064GCC1	Samsung	Samsung

FLASH/SSD PART NUMBERS

FORM FACTOR	INTERFACE	TEMP	CAPACITY	VIKING PN#	CONTROLLER	NAND
eMMC	eMMC	0°C to+70°C	32	VSFEMMC032GCCD	Samsung	Samsung
eMMC	eMMC	0°C to+70°C	32	VSFEMMC032GCC1	Samsung	Samsung
eMMC	eMMC	0°C to+70°C	16	VSFEMMC016GCCD	Samsung	Samsung
eUSB	USB 2.0	0°C to+70°C	8	VRFUSB28192ACRB1	HyperstoneU8	TBD
eUSB	USB 2.0	0°C to+70°C	4	VRFUSB24096ACQB1	HyperstoneU8	TBD
eUSB	USB 2.0	0°C to+70°C	256	VRFUSB2256GACCS1	HyperstoneU8	TBD
eUSB	USB 2.0	0°C to+70°C	128	VRFUSB2128GACZTLS1	HyperstoneU8	TSB MLC
eUSB	USB 2.0	0°C to+70°C	128	VRFUSB2128GACZS*	HyperstoneU8	TBD
eUSB	USB 2.0	0°C to+70°C	64	VRFUSB2064GACATLS1	HyperstoneU8	TSB MLC
eUSB	USB 2.0	0°C to+70°C	65	VRFUSB2064GACAS1	HyperstoneU8	TBD
eUSB	USB 2.0	0°C to+70°C	65	VRFUSB2064GACAMTL	HyperstoneU8	TSB MLC
eUSB	USB 2.0	0°C to+70°C	8	VRFDUC3L8192ACQ3TH	HyperstoneU8	TSB 24nm SLC
eUSB	USB 2.0	0°C to+70°C	16	VRFDUC3L016GACR3TH	HyperstoneU8	TSB 24nm SLC
eUSB	USB 2.0	0°C to+70°C	8	VRFDUC38192ZCD0*	eMMC TTM	eMMC TTM
eUSB	USB 2.0	0°C to+70°C	8	VRFDUC38192ACQTH	HyperstoneU8	TSB 24nm SLC
eUSB	USB 2.0	0°C to+70°C	16	VRFDUC3016GZCB0*	eMMC TTM	eMMC TTM
eUSBLowProfile	USB2.0	0°C to+70°C	8	VRFDUC3L8192ACQ3TH	SMI3252	TSB 24nm SLC
eUSBLowProfile	USB2.0	0°C to+70°C	4	VRFDUC3L4096YCH3A6	SMI3252	TSB 24nm SLC
eUSBLowProfile	USB2.0	0°C to+70°C	2	VRFDUC3L2048YCE3A8	SMI3252	TSB 24nm SLC
eUSBLowProfile	USB2.0	-40°C to+85°C	30	VRFDUC3L030GAISTH	HyperstoneU8	TSB 24nm SLC
eUSBLowProfile	USB2.0	0°C to+70°C	30	VRFDUC3L030GACSTH	HyperstoneU8	TSB 24nm SLC
eUSBLowProfile	USB2.0	0°C to+70°C	16	VRFDUC3L016GACR3TH	HyperstoneU8	TSB 24nm SLC
eUSBStdProfile	USB2.0	-40°C to+85°C	8	VRFDUC38192AISTH	HyperstoneU8	TSB 24nm SLC
eUSBStdProfile	USB2.0	0°C to+70°C	8	VRFDUC38192ACQTH	HyperstoneU8	TSB 24nm SLC
eUSBStdProfile	USB2.0	-40°C to+85°C	30	VRFDUC3030GAISTH	HyperstoneU8	TSB 24nm SLC
eUSBStdProfile	USB2.0	0°C to+70°C	30	VRFDUC3030GACSTH	HyperstoneU8	TSB 24nm SLC
eUSBStdProfile	USB2.0	-40°C to+85°C	16	VRFDUC3016GAISTH	HyperstoneU8	TSB 24nm SLC
eUSBStdProfile	USB2.0	0°C to+70°C	16	VRFDUC3016GACSTH	HyperstoneU8	TSB 24nm SLC
M.2 PCIe	2280	0°C to+70°C	512	VWFNP5512G2EHWW3	WD	TSB BiCS 3D
M.2 PCIe	2280	0°C to+70°C	256	VWFNP5256G2E5WW3	WD	TSB BiCS 3D
M.2 PCIe	2280	0°C to+70°C	2000	VWFNP5002T2ELWW4	WD	TSB BiCS 3D
M.2 PCIe	2280	0°C to+70°C	1000	VWFNP5001T2EFWW3	WD	TSB BiCS 3D
M.2 PCIe	2230	0°C to+70°C	512	VWFNP3512G2CFWWW3	WD	TSB BiCS 3D
M.2 PCIe	2280	-40°C to+85°C	1920	VRFNP51T92JILWW4	SM2262	TSB BiCS 3D
M.2 PCIe	110mm	0°C to+70°C	960	VSFNP7960GHC4WSA	Samsung	Samsung
M.2 PCIe	110mm	0°C to+70°C	3840	VSFNP73T84HC8WSA	Samsung	Samsung
M.2 PCIe	110mm	0°C to+70°C	1920	VSFNP71T92HC8WSA	Samsung	Samsung
M.2 PCIe	2242	-40°C to+85°C	960	VRFNP6960GKI4WT3	SM2263XT	TSB BiCS 3D
M.2 PCIe	2242	0°C to+70°C	960	VRFNP6960GKC4WT3	SM2263XT	TSB BiCS 3D
M.2 PCIe	2242	-40°C to+85°C	480	VRFNP6480GKIFWT3	SM2263XT	TSB BiCS 3D
M.2 PCIe	2242	0°C to+70°C	480	VRFNP6480GKCFWT3	SM2263XT	TSB BiCS 3D
M.2 PCIe	2242	-40°C to+85°C	240	VRFNP6240GKIHWT3	SM2263XT	TSB BiCS 3D
M.2 PCIe	2242	0°C to+70°C	240	VRFNP6240GKCHWT3	SM2263XT	TSB BiCS 3D
M.2 PCIe	2242	-40°C to+85°C	120	VRFNP6120GKI5WT3	SM2263XT	TSB BiCS 3D
M.2 PCIe	2242	0°C to+70°C	120	VRFNP6120GKC5WT3	SM2263XT	TSB BiCS 3D
M.2 PCIe	2242	-40°C to+85°C	60	VRFNP6060GKI5WT3	SM2263XT	TSB BiCS 3D
M.2 PCIe	2242	0°C to+70°C	60	VRFNP6060GKC5WT3	SM2263XT	TSB BiCS 3D
M.2 PCIe	2280	-40°C to+85°C	480	VRFNP5480GKIHWT3	SM2263XT	TSB BiCS 3D

FLASH/SSD PART NUMBERS

FORM FACTOR	INTERFACE	TEMP	CAPACITY	VIKING PN#	CONTROLLER	NAND
M.2 PCIe	2280	0°C to+70°C	480	VRFNP5480GKCHWT3	SM2263XT	TSB BiCS 3D
M.2 PCIe	2280	-40°C to+85°C	240	VRFNP5240GKI5WT3	SM2263XT	TSB BiCS 3D
M.2 PCIe	2280	0°C to+70°C	240	VRFNP5240GKC5WT3	SM2263XT	TSB BiCS 3D
M.2 PCIe	2280	-40°C to+85°C	120	VRFNP5120GKI5WT3	SM2263XT	TSB BiCS 3D
M.2 PCIe	2280	0°C to+70°C	120	VRFNP5120GKC5WT3	SM2263XT	TSB BiCS 3D
M.2 PCIe	2280	-40°C to+85°C	60	VRFNP5060GKI5WT3	SM2263XT	TSB BiCS 3D
M.2 PCIe	2280	0°C to+70°C	60	VRFNP5060GKC5WT3	SM2263XT	TSB BiCS 3D
M.2 SATA	2280	0°C to+70°C	512	VWFEM5512G2CHWW3	WD	TSB BiCS 3D
M.2 SATA	2280	0°C to+70°C	256	VWFEM5256G2C5WW3	WD	TSB BiCS 3D
M.2 SATA	2280	0°C to+70°C	1000	VWFEM5001T2CFWW3	WD	TSB BiCS 3D
M.2 SATA	2242	-40°C to+85°C	480	VRFEM6480GEIFWT3	SM2259	TSB BiCS 3D
M.2 SATA	2242	0°C to+70°C	480	VRFEM6480GECFWT3	SM2259	TSB BiCS 3D
M.2 SATA	2242	-40°C to+85°C	240	VRFEM6240GEIHWT3	SM2259	TSB BiCS 3D
M.2 SATA	2242	0°C to+70°C	240	VRFEM6240GECHWT3	SM2259	TSB BiCS 3D
M.2 SATA	2242	-40°C to+85°C	120	VRFEM6120GEI5WT3	SM2259	TSB BiCS 3D
M.2 SATA	2242	0°C to+70°C	120	VRFEM6120GEC5WT3	SM2259	TSB BiCS 3D
M.2 SATA	2242	-40°C to+85°C	60	VRFEM6060GEI5WT3	SM2259	TSB BiCS 3D
M.2 SATA	2242	0°C to+70°C	60	VRFEM6060GEC5WT3	SM2259	TSB BiCS 3D
M.2 SATA	2280	-40°C to+85°C	960	VRFEM5960GEIFWT3	SM2259	TSB BiCS 3D
M.2 SATA	2280	-40°C to+85°C	480	VRFEM5480GEIHWT3	SM2259	TSB BiCS 3D
M.2 SATA	2280	-40°C to+85°C	240	VRFEM5240GEI5WT3	SM2259	TSB BiCS 3D
M.2 SATA	2280	-40°C to+85°C	120	VRFEM5120GEI5WT3	SM2259	TSB BiCS 3D
M.2 SATA	2280	-40°C to+85°C	60	VRFEM5060GEI5WT3	SM2259	TSB BiCS 3D
M.2 SATA	2260	-40°C to+85°C	960	VRFEM4960GEIFWT3	SM2259	TSB BiCS 3D
M.2 SATA	2260	0°C to+70°C	960	VRFEM4960GECFWT3	SM2259	TSB BiCS 3D
M.2 SATA	2260	-40°C to+85°C	480	VRFEM4480GEIHWT3	SM2259	TSB BiCS 3D
M.2 SATA	2260	0°C to+70°C	480	VRFEM4480GECHWT3	SM2259	TSB BiCS 3D
M.2 SATA	2260	-40°C to+85°C	240	VRFEM4240GEI5WT3	SM2259	TSB BiCS 3D
M.2 SATA	2260	0°C to+70°C	240	VRFEM4240GEC5WT3	SM2259	TSB BiCS 3D
M.2 SATA	2260	-40°C to+85°C	120	VRFEM4120GEI5WT3	SM2259	TSB BiCS 3D
M.2 SATA	2260	0°C to+70°C	120	VRFEM4120GEC5WT3	SM2259	TSB BiCS 3D
M.2 SATA	2260	-40°C to+85°C	60	VRFEM4060GEI5WT3	SM2259	TSB BiCS 3D
M.2 SATA	2260	0°C to+70°C	60	VRFEM4060GEC5WT3	SM2259	TSB BiCS 3D
mSATA	MO300	-40°C to+85°C	960	VRFEM2960GEIFWT3	SM2259	TSB BiCS 3D
mSATA	MO300	-40°C to+85°C	480	VRFEM2480GEIHWT3	SM2259	TSB BiCS 3D
mSATA	MO300	-40°C to+85°C	240	VRFEM2240GEI5WT3	SM2259	TSB BiCS 3D
mSATA	MO300	-40°C to+85°C	120	VRFEM2120GEI5WT3	SM2259	TSB BiCS 3D
mSATA	MO300	-40°C to+85°C	60	VRFEM2060GEI5WT3	SM2259	TSB BiCS 3D
SD Card	microSD	0°C to+70°C	32	VWUSD032GCEBMML	WD	SanDisk MLC
SD Card	microSD	-25°C to+85°C	32	VWUSD032GCE1WW3C	WD	TSB BiCS 3D
SD Card	microSD	0°C to+70°C	32	VWUSD032GCE1WW3C	WD	TSB BiCS 3D
SD Card	microSD	0°C to+70°C	8	VWFUSD8192CEWWW	WD	TSB BiCS 3D
SD Card	microSD	-25°C to+85°C	256	VWFUSD256GCECMWL	WD	SanDisk MLC
SD Card	microSD	-25°C to+85°C	128	VWFUSD128GCEZMWL	WD	SanDisk MLC
SD Card	microSD	-25°C to+85°C	64	VWFUSD064GCEAMWL	WD	SanDisk MLC
SD Card	Full Size SD	-40°C to+85°C	128	VWFSD3128GCIZMWL	WD	SanDisk MLC
SD Card	Full Size SD	-25°C to+85°C	128	VWFSD3128GCEZMWL	WD	SanDisk MLC
SD Card	Full Size SD	-40°C to+85°C	64	VWFSD3064GCIAMWL	WD	SanDisk MLC

FLASH/SSD PART NUMBERS

FORM FACTOR	INTERFACE	TEMP	CAPACITY	VIKING PN#	CONTROLLER	NAND
SD Card	Full Size SD	-25°C to+85°C	64	VWFSD3064GCEAMWL	WD	SanDisk MLC
SD Card	microSD	-25°C to+85°C	64	VAFUSD064GCEAMTL	SMI3268	TSB BiCS 3D
SD Card	microSD	-25°C to+85°C	16	VAFUSD016GCEDMTL	PS8210	TSB BiCS 3D
SD Card	Full Size SD	-25°C to+85°C	64	VAFSD3064GCC5MTL	SMI3268	SanDisk MLC
SD Card	Full Size SD	-25°C to+85°C	32	VAFSD3032GCCBMTL	SMI3268	SanDisk MLC
slimSATA	MO297	-40°C to+85°C	960	VRFEM1960GEIFWT3	SM2259	TSB BiCS 3D
slimSATA	MO297	-40°C to+85°C	480	VRFEM1480GEIHWT3	SM2259	TSB BiCS 3D
slimSATA	MO297	-40°C to+85°C	240	VRFEM1240GEI5WT3	SM2259	TSB BiCS 3D
slimSATA	MO297	-40°C to+85°C	120	VRFEM1120GEI5WT3	SM2259	TSB BiCS 3D
slimSATA	MO297	-40°C to+85°C	60	VRFEM1060GEI5WT3	SM2259	TSB BiCS 3D

DDR4 PART NUMBERS

FORM FACTOR	BUFFERING	DENSITY	ORG.	SPEED	ECC	DRAM I/O	RANK	PROFILE	PART NUMBER
288-pin DIMM	Registered	4GB	512Mbx72	2400MT/s	ECC	x8	1	LP	VR9MR127228HBJ
288-pin DIMM	Registered	4GB	512Mbx72	2133MT/s	ECC	x8	1	LP	VR9MR127228HBH
288-pin DIMM	Registered	8GB	1Gbx72	2400MT/s	ECC	x8	1	LP	VR9MR1G7228JBJ
288-pin DIMM	Registered	8GB	1Gbx72	2666MT/s	ECC	x8	1	LP	VR9MR1G7228JBK
288-pin DIMM	Registered	8GB	1Gbx72	2133MT/s	ECC	x8	1	LP	VR9MR1G7228JBH
288-pin DIMM	Registered	8GB	1Gbx72	2400MT/s	ECC	x8	2	LP	VR9MR1G7228HBJ
288-pin DIMM	Registered	8GB	1Gbx72	2133MT/s	ECC	x8	2	LP	VR9MR1G7228HBH
288-pin DIMM	Registered	8GB	1Gbx72	2400MT/s	ECC	x4	1	LP	VR9MR1G7224HBJ
288-pin DIMM	Registered	8GB	1Gbx72	2133MT/s	ECC	x4	1	LP	VR9MR1G7224HBH
288-pin DIMM	Registered	16GB	2Gbx72	2400MT/s	ECC	x8	2	LP	VR9MR2G7228JBJ
288-pin DIMM	Registered	16GB	2Gbx72	2667MT/s	ECC	x8	2	LP	VR9MR2G7228JBK
288-pin DIMM	Registered	16GB	2Gbx72	2133MT/s	ECC	x8	2	LP	VR9MR2G7228JBH
288-pin DIMM	Registered	16GB	2Gbx72	2400MT/s	ECC	x4	2	LP	VR9MR2G7224HBJ
288-pin DIMM	Registered	16GB	2Gbx72	2133MT/s	ECC	x4	2	LP	VR9MR2G7224HBH
288-pin DIMM	Registered	32GB	4Gbx72	2400MT/s	ECC	x4	2	LP	VR9MR4G7224JBJ
288-pin DIMM	Registered	16GB	2Gbx72	2667MT/s	ECC	x4	1	LP	VR9MR2G7224JBK
288-pin DIMM	Registered	16GB	2Gbx72	2133MT/s	ECC	x4	1	LP	VR9MR2G7224JBH
288-pin DIMM	Registered	32GB	4Gbx72	2133MT/s	ECC	x4	2	LP	VR9MR4G7224JBH
288-pin DIMM	Registered	16GB	2Gx72	2133MT/s	ECC	x4	2	LP	VR9MR2G7224HBH
288-pin DIMM	Registered	32GB	4Gx72	2667MT/s	ECC	x4	2	LP	VR9MR4G7224JBK
288-pin DIMM	Registered	64GB	8Gbx72	2400MT/s	ECC	x4	4	LP	VR9MR8G7224JEJ
288-pin DIMM	Registered	8GB	1Gx72	2400MT/s	ECC	x8	1	LP	VR9MR1G7228JBJ
288-pin DIMM	Registered	4GB	512Mbx72	2400MT/s	ECC	x8	1	VLP	VR9VR127228HBJ
288-pin DIMM	Registered	4GB	512Mbx72	2133MT/s	ECC	x8	1	VLP	VR9VR127228HBH
288-pin DIMM	Registered	8GB	1Gbx72	2400MT/s	ECC	x4	1	VLP	VR9VR1G7224HBJ
288-pin DIMM	Registered	8GB	1Gbx72	2133MT/s	ECC	x4	1	VLP	VR9VR1G7224HBH
288-pin DIMM	Registered	8GB	1Gbx72	2400MT/s	ECC	x8	1	VLP	VR9VR1G7228JBJ
288-pin DIMM	Registered	8GB	1Gbx72	2133MT/s	ECC	x8	1	VLP	VR9VR1G7228JBH
288-pin DIMM	Registered	16GB	2Gbx72	2400MT/s	ECC	x4	1	VLP	VR9VR2G7224JBJ
288-pin DIMM	Registered	16GB	2Gbx72	2133MT/s	ECC	x4	1	VLP	VR9VR2G7224JBH
288-pin DIMM	Registered	16GB	2Gbx72	2400MT/s	ECC	x8	2	VLP	VR9VR2G7228JBJ
288-pin DIMM	Registered	16GB	2Gbx72	2133MT/s	ECC	x8	2	VLP	VR9VR2G7228JBH
288-pin DIMM	Registered	32GB	4Gbx72	2133MT/s	ECC	x4	2	VLP	VR9VR4G7224JHH
288-pin DIMM	Registered	32GB	4Gbx72	2667MT/s	ECC	x4	2	VLP	VR9VR4G7224JHK

DDR4 PART NUMBERS

FORM FACTOR	BUFFERING	DENSITY	ORG.	SPEED	ECC	DRAM I/O	RANK	PROFILE	PART NUMBER
288-pin DIMM	Unbuffered	4GB	512Mbx64	2400MT/s	None	x8	1	LP	VR9MU126428HBJ
288-pin DIMM	Unbuffered	4GB	512Mbx64	2667MT/s	None	x8	1	LP	VR9MU126428HBK
288-pin DIMM	Unbuffered	4GB	512Mbx64	2133MT/s	None	x8	1	LP	VR9MU126428HBH
288-pin DIMM	Unbuffered	4GB	512Mbx72	2400MT/s	ECC	x8	1	LP	VR9MU127228HBJ
288-pin DIMM	Unbuffered	4GB	512Mbx72	2133MT/s	ECC	x8	1	LP	VR9MU127228HBH
288-pin DIMM	Unbuffered	4GB	512Mbx72	2667MT/s	ECC	x8	1	LP	VR9MU127228HBK
288-pin DIMM	Unbuffered	4GB	512Mbx72	2400MT/s	ECC	x8	1	LP	VR9MU127228HBJ
288-pin DIMM	Unbuffered	8GB	1Gbx64	2400MT/s	None	x8	2	LP	VR9MU1G6428HBJ
288-pin DIMM	Unbuffered	8GB	1Gbx64	2133MT/s	None	x8	2	LP	VR9MU1G6428HBH
288-pin DIMM	Unbuffered	8GB	1Gbx64	2400MT/s	None	x8	1	LP	VR9MU1G6428JBJ
288-pin DIMM	Unbuffered	8GB	1Gbx64	2667MT/s	None	x8	1	LP	VR9MU1G6428JBK
288-pin DIMM	Unbuffered	8GB	1Gbx64	2133MT/s	None	x8	1	LP	VR9MU1G6428JBH
288-pin DIMM	Unbuffered	16GB	2Gbx72	2133MT/s	ECC	x8	2	LP	VR9MU2G7228JBH
288-pin DIMM	Unbuffered	16GB	2Gbx72	2400MT/s	ECC	x8	2	LP	VR9MU2G7228JBJ
288-pin DIMM	Unbuffered	16GB	2Gbx72	2667MT/s	ECC	x8	2	LP	VR9MU2G7228JBK
288-pin DIMM	Unbuffered	8GB	1Gbx72	2400MT/s	ECC	x8	2	LP	VR9MU1G7228HBJ
288-pin DIMM	Unbuffered	8GB	1Gbx72	2133MT/s	ECC	x8	2	LP	VR9MU1G7228HBH
288-pin DIMM	Unbuffered	8GB	1Gbx72	2400MT/s	ECC	x8	1	LP	VR9MU1G7228JBJ
288-pin DIMM	Unbuffered	8GB	1Gbx72	2133MT/s	ECC	x8	1	LP	VR9MU1G7228JBH
288-pin DIMM	Unbuffered	8GB	1Gbx72	2667MT/s	ECC	x8	1	LP	VR9MU1G7228JBK
288-pin DIMM	Unbuffered	16GB	2Gbx64	2400MT/s	None	x8	2	LP	VR9MU2G6428JBJ
288-pin DIMM	Unbuffered	16GB	2Gbx64	2133MT/s	None	x8	2	LP	VR9MU2G6428JBH
288-pin DIMM	Unbuffered	16GB	2Gbx72	2400MT/s	ECC	x8	2	LP	VR9MU1G7228JBJ
288-pin DIMM	Unbuffered	16GB	2Gbx72	2133MT/s	ECC	x8	2	LP	VR9MU1G7228JBH
288-pin DIMM	Unbuffered	8GB	1Gbx72	2400MT/s	ECC	x8	2	VLP	VR9VU1G7228HBJ
288-pin DIMM	Unbuffered	8GB	1Gbx72	2133MT/s	ECC	x8	2	VLP	VR9VU1G7228HBH
288-pin DIMM	Unbuffered	8GB	1Gbx72	2400MT/s	ECC	x8	2	VLP	VR9VU1G7228JBJ
288-pin DIMM	Unbuffered	16GB	2Gbx72	2400MT/s	ECC	x8	2	VLP	VR9VU2G7228JBJ
288-pin DIMM	Unbuffered	16GB	2Gbx72	2133MT/s	ECC	x8	2	VLP	VR9VU2G7228JBH
288-pin ULP DIMM	Registered	16GB	2Gx72	2133MT/s	ECC	x8	2	VLP	VR9UR2G7228JBH
260-pin SODIMM	Unbuffered	4GB	512Mbx64	2400MT/s	None	x8	1	LP	VR9FU126428HBJ
260-pin SODIMM	Unbuffered	4GB	512Mbx64	2133MT/s	None	x8	1	LP	VR9FU126428HBH
260-pin SODIMM	Unbuffered	4GB	512Mbx72	2400MT/s	ECC	x8	1	LP	VR9FU127228HBJ

Not a complete list of DDR4 Part Numbers

*Viking Technology offers a full portfolio of DRAM modules from DDR4 down to legacy DDR1 memory solutions with support in every form factor, capacity, and configuration in each technology interface.

For all inquiries in DDR3, DDR2, and DDR1, please contact your sales manager for detailed part number and configuration or email us at **sales@vikingtechnology.com**.

NOTES

For sales information, email us at sales@vikingtechnology.com, or visit our website for all global locations and contact information.

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